Special Issue

Nanoscale Assembly and Integration for Applications

Message from the Guest Editor

Nanoscale materials and applications now occupy a central role in research and commercial products ranging from electronics and biotechnology to automobiles and aircrafts. The field continues to grow at a rapid pace fueled by a global effort—involving governments, academia and industry—that has been enabled by advances in nanofabrication, which underpins the application of nanoscale materials. A key challenge in nanofabrication is the control and integration of structures as desired in order to deliver novel materials and applications at the nanoscale (~1 to 100 nm). By controllably assembling nanomaterials, their excellent properties can be harnessed for enhanced performance and emerging applications in computing, information technology, energy, sensing, health and security.

Guest Editor

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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